

# 2SK2492-VB Datasheet N-Channel 150-V (D-S) 175 °C MOSFET

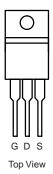
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)		
150	0.030 at V <sub>GS</sub> = 10 V	50		
150	0.033 at V <sub>GS</sub> = 6 V	45		

## **FEATURES**

- Trench Power MOSFETs
- 175 °C Junction Temperature
- New Low Thermal Resistance Package
- PWM Optimized
- Compliant to RoHS Directive 2002/95/EC

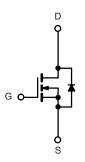


#### TO-220AB



## **APPLICATIONS**

Primary Side Switch



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T <sub>C</sub> = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	150	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	V		
Continuous Drain Current (T <sub>.1</sub> = 175 °C)	T <sub>C</sub> = 25 °C	L	50	<b>A</b>	
Continuous Diam Current (1) = 175 C)	T <sub>C</sub> = 125 °C	- ID	35		
Pulsed Drain Current	I <sub>DM</sub>	150	Α		
Avalanche Current		I <sub>AR</sub>	50		
Repetitive Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AR</sub>	80	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	В	166 <sup>b</sup>	w	
	T <sub>A</sub> = 25 °C <sup>c</sup>	$ P_{D}$	3.75		
Operating Junction and Storage Temperature Ra	ange	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)	R <sub>thJC</sub>	0.9	C/VV	

### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

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<b>SPECIFICATIONS</b> $T_J = 25^{\circ}$	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		1001001110110		.,,,,		<u> </u>	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	150				
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2		4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μΑ	
		V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	80			Α	
	` '	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A		0.030			
	_	V <sub>GS</sub> = 6 V, I <sub>D</sub> = 10 A		0.033			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 125 °C		0.076		Ω	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 175 °C		0.100			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A	10			S	
Dynamic <sup>b</sup>				<u> </u>			
Input Capacitance	C <sub>iss</sub>			2500		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		290			
Reverse Transfer Capacitance	C <sub>rss</sub>			190			
Gate Resistance	$R_{g}$			2		Ω	
Total Gate Charge <sup>c</sup>	$Q_g$			38	60		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 40 \text{ A}$		13		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{\mathrm{gd}}$			13			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 75 \text{ V}, R_L = 1.80 \Omega$		130	200		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 40 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		30	45	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			90	140		
Source-Drain Diode Ratings and Characteristics T <sub>C</sub> = 25 °C <sup>b</sup>							
Continuous Current	IS				40	^	
Pulsed Current	I <sub>SM</sub>				80 A		
Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>F</sub> = 40 A, V <sub>GS</sub> = 0 V		1.0	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			100	150	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 40 A, dl/dt = 100 A/μs		5	8	Α	
Reverse Recovery Charge	Q <sub>rr</sub>			0.25	0.6	μC	

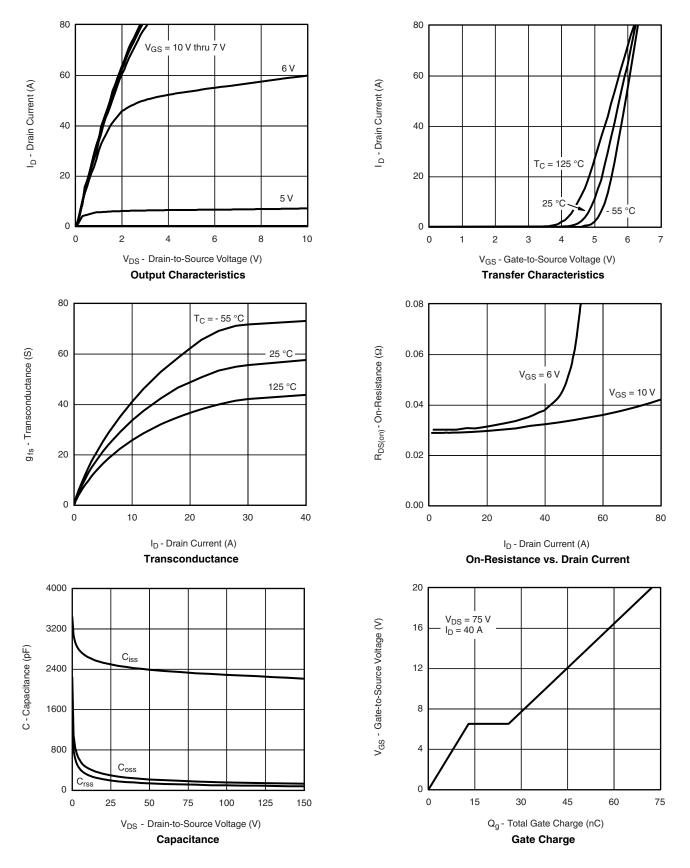
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



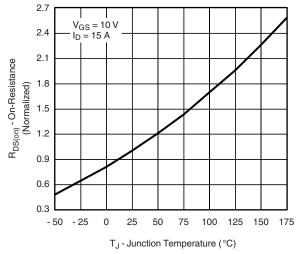
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

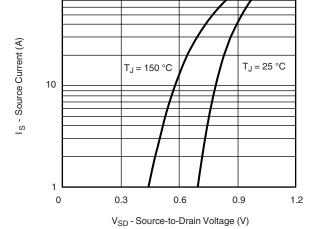


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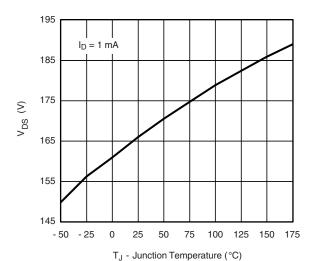




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On-Resistance vs. Junction Temperature

Source-Drain Diode Forward Voltage

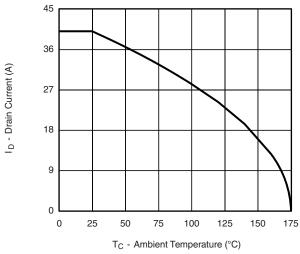


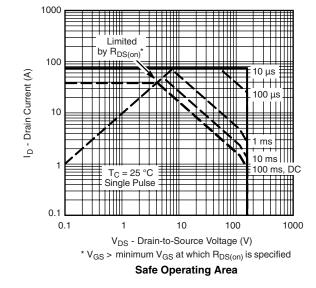
Drain Source Breakdown vs. Junction Temperature

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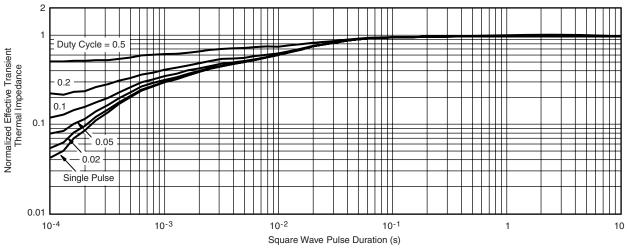


## THERMAL RATINGS





Maximum Avalanche and Drain Current vs. Case Temperature



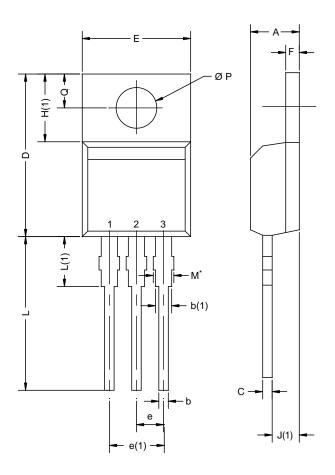
Normalized Thermal Transient Impedance, Junction-to-Case

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## **TO-220AB**



	MILLIM	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0208-Rev. N, 08-Oct-12					

ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471

## Notes

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 $<sup>^{\</sup>star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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